

ABSTRACT

The disclosure relates to the technical field of wafer grinding, in particular to a grinding head and a wafer grinding apparatus having the same. The grinding head includes: a main body, wherein a first flexible membrane chamber and a second flexible membrane chamber are sequentially arranged in the main body along a direction of force application; a force application structure, at a junction of the first flexible membrane chamber and the second flexible membrane chamber, and extending to be adjacent to an outer periphery of a working surface of the second flexible membrane chamber; the force application structure having: a first state, in which the force application structure exerts a force on the outer periphery of the working surface of the second flexible membrane chamber under air pressure in the first flexible membrane chamber, so that it presses a periphery of a workpiece; and a second state, in which a gap is provided between the force application structure and the outer periphery of the working surface of the second flexible membrane chamber where the first flexible membrane chamber is not pressurized. The disclosure provides the grinding head and the wafer grinding apparatus having the same, so that the wafer is more planarized, uniform and consistent after grinding.

[Fig. 1]